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REMARKS

In the October 13, 2005 Final Office Action, the Examiner noted Claims 1-14 are pending in the application. The Examiner rejected Claims 1-11 and acknowledged the withdrawal of Claims 12-14. By this Response, all rejected claims continue unamended and arguments refuting the Examiner's positions are provided. In view of the following discussion, the Applicant submits that none of the claims now pending in the application are obvious under the provision of 35 U.S.C. §103. Accordingly, the Applicant requests that the Examiner enter this Response and reconsider the application.

REJECTIONS

The Examiner has rejected claims 1-7 and 9-11 under 35 U.S.C. §103(a) as being unpatentable over US Patent No. 6,268,236 issued to Miyawaki in view of US Patent No. 4,897,508 issued to Mahulikar et al, (hereinafter "Miyawaki" and "Mahulikar" respectively). The Applicant respectfully traverses the rejection.

The Examiner contends Miyawaki discloses a method of packaging at least one component, comprising: providing a lid 2; molding sidewalls 1B, for example onto a substrate to form a plurality of cavities 4 surrounding a component-mounting surface; mounting a component 7 on the component-mounting surface in each capacity, applying a curable adhesive 3 to a top surface of the sidewalls; placing the lid upon the surface of the sidewall; curing said adhesive; and separating the component package into a plurality of individual component packages. The Examiner concedes that Miyawaki does not teach the lid having vent holes. Further, the Examiner cites Mahulikar as teaching an analogous package including a substrate 12, cavity 30, and a component 22 in the cavity, adhesive layer to attach a lid 14 to the substrate. The Examiner further contends the lid comprises a vent hole 44 for releasing reaction by-products generated during the cure cycle. The Examiner concludes

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that a combination of the teachings of Miyawaki and Mahulikar teaches the Applicant's invention. The Applicant respectfully disagrees.

More specifically, Miyawaki clearly teaches at Col. 2, line 66 – Col. 3, line 1 that the base package substrate 1 is created by adhering ("bonding") a lower first substrate 1A to an upper second substrate 1B (i.e., a substrate with a grid-like pattern of rectangular holes"). Both the lower first substrate and upper second substrate are formed (molded) prior to them being adhered to one another. Further, at Col. 3, lines 8-10, the reference teaches, "(t)hrough holes or penetrating holes are formed in the second (upper) substrate 1B in order to produce hollow cavities". Thus, the layer 1B is preformed as a sheet and then later punched or otherwise cut with holes to arrive at the final layer having a grid-like structure. At Col. 3, line 10, the substrates are "stacked" to define the cavities. Clearly, to "stack" the substrates 1A and 1B, they must be preformed, i.e., the substrate 1B is not molded onto the substrate 1A as the Applicant's claim.

A similar argument holds regarding the alleged teachings of Mahulikar. Specifically, by inspection of any of FIGS. 1, 3 or 4 (and the corresponding written descriptions) it is clear that Mahulikar teaches fastening a leadframe 16 to a base 12 with a first sealant 28 and subsequently fastening a cover component 14 to the leadframe 16 with a second sealant 26 that has the same composition as the first sealant (see at least Col 3, lines 21-24 and Col. 4, lines 8-12). The reference distinctly teaches nothing more than sealants applied for bonding purposes. As such, it is respectfully submitted that one skilled in the art would not be led by the combination of cited references to create a molded package in the manner claimed. Any combination of the cited references would adhere a pre-formed grid to a substrate to define the cavities.

Neither Miyawaki nor Mahulikar, together or singly, teach the step of "molding sidewalls onto a substrate to form a plurality of cavities surrounding a component-mounting surface". The Applicant's invention uses a single step to

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mold the sidewalls directly to the substrate, then cures the sidewalls. The prior art references form a grid of holes in one substrate, then adhere the gridded substrate to a base substrate. The Applicant's invention performs the creation of cavities in a single step – molding the sidewalls directly onto the substrate. One example of a process for molding the sidewalls is an injection molding process. In this Applicant's invention, there is no pre-forming of a gridded substrate and no adhesive used to adhere the gridded substrate to the base substrate as is taught by the prior art. None of the references teach "molding" the sidewalls onto a substrate.

Consequently, Miyawaki and Mahulikar, either alone or in combination, fail to teach or suggest the Applicant's invention as a whole. The Applicant respectfully offers that the Examiner has not properly applied the combination of cited references so as to establish the prima facie case of obviousness. Specifically, the Examiner identified Miyawaki as allegedly teaching various steps of packaging a component with the exception of disclosing a lid with vent holes. The Examiner then applied alleged teachings of Mahulikar to show a vent hole and the sealing of same in a lid as part of an analogous packaging method and combined the references to show obviousness. It is respectfully submitted that the alleged teachings of Miyawaki do not in fact teach or suggest the various steps as indicated by the Examiner. Therefore, regardless of the specific combination offered, the references are still deficient so as to not render the claims obvious.

Accordingly, the combination of Miyawaki and Mahulikar does not teach, disclose or suggest the invention of independent Claim 1; thus, the combination does not obviate the subject invention as claimed. As such, the Applicant submits that Claim 1 is not obvious and fully satisfies the requirements of 35 U.S.C. §103 and is patentable thereunder. Furthermore, Claims 2-7 and 9-11 depend either directly or indirectly from independent Claim 1 and recite additional features thereof. As such and at least for the same reasons as discussed above,

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Applicant submits that the dependent claims are also not obvious and fully satisfies the requirements of 35 U.S.C. §103 and are patentable thereunder. Therefore, the Applicant respectfully requests that the Examiner's rejection be withdrawn.

Rejection of Claims under 35 U.S.C. § 103 – Claim 8

The Examiner has rejected Claim 8 under 35 U.S.C. §103(a) as being unpatentable over Miyawaki and Mahulikar in further view of US Patent No. 5,776,799 issued to Song (hereinafter "Song"). The Applicant respectfully traverses the rejection. Specifically, Applicant has hereinabove presented the deficiencies in the teachings and combination of Miyawaki and Mahulikar. It is respectfully submitted that Song does not close the substantial gap in the cited references to support a finding of obviousness to the subject invention. That is, forming an adhesive layer by screen printing does not (either alone or in combination with the other cited references) teach or suggest a packaging method step of molding sidewalls onto a substrate to form a plurality of cavities as claimed. As such and at least for the same reasons as discussed above, Applicant submits that dependent claim 8 is not obvious and fully satisfies the requirements of 35 U.S.C. §103 and is patentable thereunder. Therefore, the Applicant respectfully requests that the Examiner's rejection be withdrawn.

Conclusion

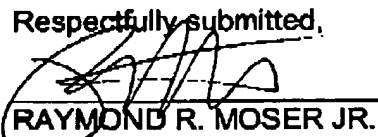
Thus, the Applicant submits that Claims 1-11 are in condition for allowance. Accordingly, both reconsideration of this application and its swift passage to issue are earnestly solicited.

If, however, the Examiner believes that there are any unresolved issues requiring adverse final action in any of the claims now pending in the application, it is requested that the Examiner telephone Mr. Raymond R. Moser, Jr., Esq. at

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(732) 935-7100 so that appropriate arrangements can be made for resolving such issues as expeditiously as possible.

Respectfully submitted,



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